



# SOT1168-1

DFN3314-16: plastic, thermal enhanced ultra thin small outline package; no leads; 16 terminals

8 February 2016

Package information

## 1. Package summary

Terminal position code	D (double)
Package type descriptive code	HUSON6
Package type industry code	DFN3314-16
Package style descriptive code	HUSON (thermal enhanced ultra thin small outline; no leads)
Package style suffix code	NA (not applicable)
Package body material type	P (plastic)
IEC package outline code	---
JEDEC package outline code	---
JEITA package outline code	---
Mounting method type	S (surface mount)
Issue date	22-3-2010

Table 1. Package summary

Symbol	Parameter		Min	Typ	Nom	Max	Unit
D	package length		3.2	-	3.3	3.4	mm
E	package width		1.25	-	1.35	1.45	mm
A	seated height		[tbd]	-	[tbd]	0.55	mm
e	nominal pitch		-	-	0.4	-	mm
n <sub>2</sub>	actual quantity of termination		-	-	16	-	



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2. Package outline

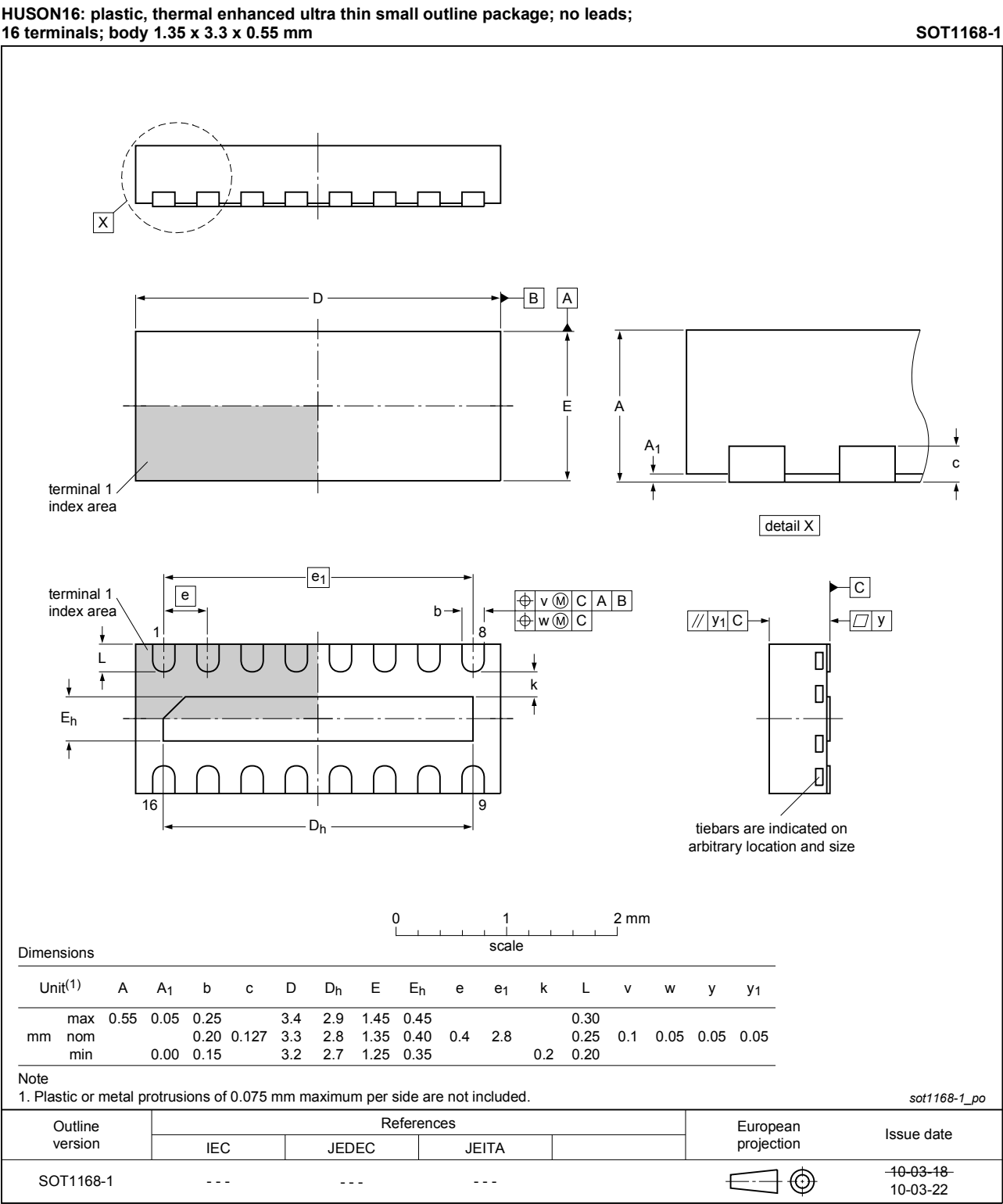
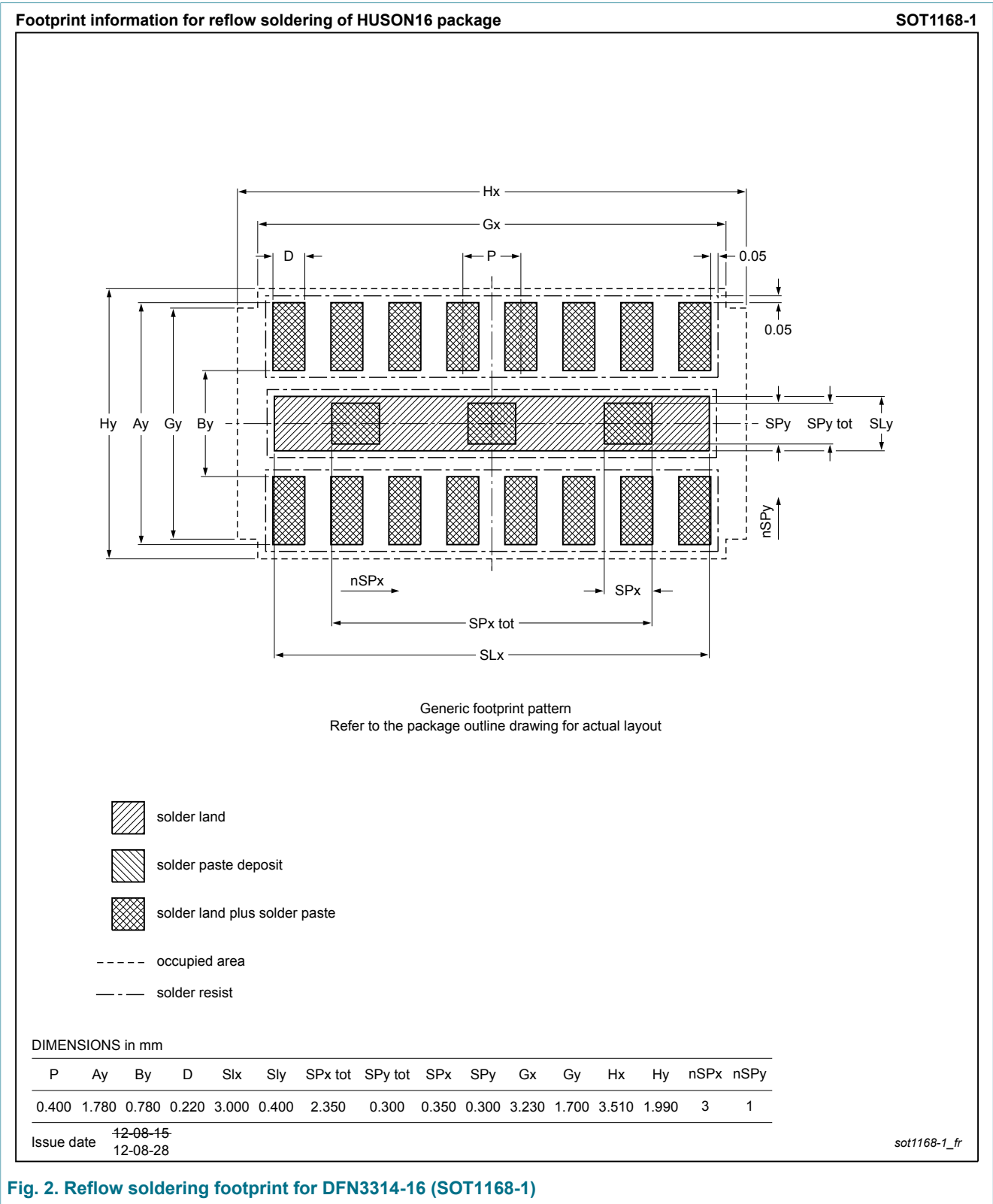


Fig. 1. Package outline DFN3314-16 (SOT1168-1)

DFN3314-16: plastic, thermal enhanced ultra thin  
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3. Soldering



## 4. Legal information

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